

1    **ABSTRACT OF THE DISCLOSURE**

2           A method for fabricating high integration multi-layer DPC lines on a  
3   ceramic board is to make the high density of multi-layer metal lines with  
4   insulating layer and the fine through holes. The metal lines are able to form in the  
5   different insulating layers, so as to the density of the metal lines is high. Besides  
6   the through holes defined in the ceramic board are fine, so that the space where  
7   the metal lines formed on is larger than the normal. Thus the fine through holes  
8   are stuffed with the conductive material, so that the quantity of the inductor of the  
9   metal lines is as possible as decreasing.